



DMMT5401

150V DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features & Benefits

- $BV_{CEO} > -150V$
- 2% Matched Tolerance, hFE, VCE(SAT), VBE(SAT)
- Ideal for Medium Power Amplification and Switching
- Dual Transistors in a Single SOT26 (SC74R) Package Taking Half the Footprint of Two Equivalent Transistors in SOT23
- **Epitaxial Planar Die Construction**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

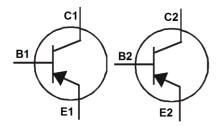
Mechanical Data

- Case: SOT26 (SC74R)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.018grams (Approximate)

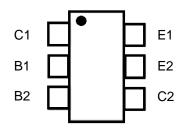
SOT26 (SC74R)







Device Symbol



Pin-Out Top

July 2017

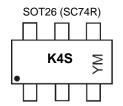
Ordering Information (Note 4)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DMMT5401-7-F	Standard	K4S	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



K4S = Part Marking (See Ordering Information)

YM = Date Code Marking Y = Year (ex: E = 2017)M = Month (ex: 9 = September)

Date Code Key

Year	2017		2018	2	2019	202	:0	2021		2022	2	2023
Code	E		F		G	Н				J		K
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-160	V
Collector-Emitter Voltage	V _{CEO}	-150	V
Emitter-Base Voltage	V_{EBO}	-5.0	V
Continuous Collector Current	lc	-200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Notes 5 & 6)	P _D	300	mW
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	417	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

			_				
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Collector-Base Breakdown Voltage	BV_{CBO}	-160	_		V	$I_C = -100\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage	BV_CEO	-150	_		V	$I_{C} = -1 \text{mA}, I_{B} = 0$	
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	_		V	$I_E = -10\mu A, I_C = 0$	
Collector-Base Cutoff Current	lana	_	_	-50	nA	$V_{CB} = -120V, I_{E} = 0$	
Collector-base Cuton Current	I _{CBO}				μΑ	$V_{CB} = -120V, I_E = 0, T_A = +100^{\circ}C$	
Emitter-Base Cutoff Current	I _{EBO}		_	-50	nA	$V_{EB} = -3V, I_B = 0$	
ON CHARACTERISTICS (Note 7)							
		50				$I_C = -1mA$, $V_{CE} = -5V$	
DC Current Gain (Note 8)	h _{FE}	60	_	240	_	$I_C = -10 \text{mA}, V_{CE} = -5 \text{V}$	
		50				$I_C = -50 \text{mA}, V_{CE} = -5 \text{V}$	
Collector-Emitter Saturation Voltage	V		_	-0.2 -0.5	V	$I_C = -10mA, I_B = -1mA$	
Collector-Efficier Saturation Voltage	V _{CE(SAT)}					$I_C = -50\text{mA}$, $I_B = -5\text{mA}$	
Base-Emitter Saturation Voltage	V _{BE(SAT)}	_	_	-1	V	$I_C = -10mA$, $I_B = -1mA$	
<u> </u>	VBE(SAT)					$I_C = -50 \text{mA}, I_B = -5 \text{mA}$	
SMALL SIGNAL CHARACTERISTICS							
Current Gain-Bandwidth Product	f⊤	100	_	300	MHz	$V_{CE} = -10V$, $I_{C} = -10mA$, $f = 100MHz$	
Output Capacitance	C _{OBO}	_	_	6	pF	$V_{CB} = -10V$, $f = 1.0MHz$, $I_{E} = 0mA$	
Small Signal Current Gain	h _{fe}	40	_	200	_	$V_{CE} = -10V, I_{C} = -1mA, f = 1.0kHz$	
Noise Figure	NF		_	8	dB	$V_{CE} = -5V$, $I_{C} = -200\mu A$, $R_{S} = 10\Omega$, $f = 1.0kHz$	

Notes:

- 5. For a device surface mounted on 1.0 x 0.75 x 0.62 inch FR-4 PCB with high coverage of copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 6. Maximum combined dissipation.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. The DC Current Gain, h_{FE}, (matched at I_C = -10mA and V_{CE} = -5V) Collector Emitter Saturation Voltage, V_{CE(SAT)}, and Base Emitter Saturation Voltage, V_{BE(SAT)} are matched with typical matched tolerances of 1% and maximum of 2%.



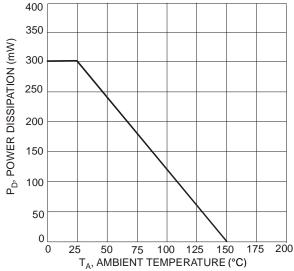


Fig. 1 Power Dissipation vs. Ambient Temperature

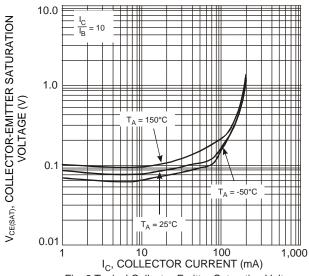


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

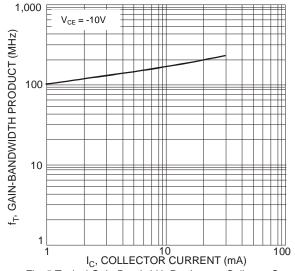


Fig. 5 Typical Gain-Bandwidth Product vs. Collector Current

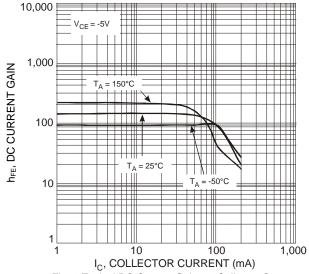
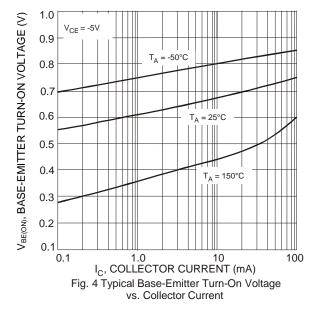


Fig. 2 Typical DC Current Gain vs. Collector Current

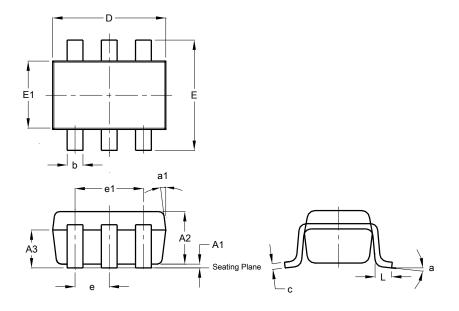




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT26 (SC74R)

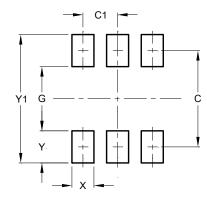


SOT26 (SC74R)						
Dim	Min	Max	Тур			
A1	0.013	0.10	0.05			
A2	1.00	1.30	1.10			
A3	0.70	0.80	0.75			
b	0.35	0.50	0.38			
С	0.10	0.20	0.15			
D	2.90	3.10	3.00			
е	-	-	0.95			
e1	-	-	1.90			
Е	2.70	3.00	2.80			
E1	1.50	1.70	1.60			
L	0.35	0.55	0.40			
а	-	-	8°			
a1	-	-	7°			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT26 (SC74R)



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



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